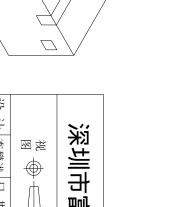


	物料	物料标签	
供应商		東 丘司宏	
規格型号			
物料编码			
装箱数量			
生产日期			

注:

- 1. 纸箱为K=K材质
- 2. 外箱表面清洁.
- 3. 此箱需通过我司IQC相关测试标准。
- 4. 每盘装5000PCS,
- 每箱装10盘,5000*10=50000PCS
- 6. 未注明公差±0. 2mm



送
出出
勘海
科技
有照
公回

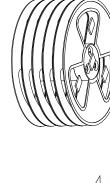
	19. 09. 04	日期	罗观彬	核	田
11. 0200		日期		C/‡	I
TE_0903		日期		对	校
	19. 09. 04	日期	李攀进	计	设
包装图	+		※ 图		

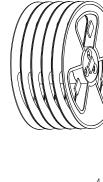


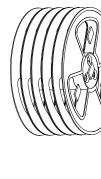
发放部门

采购部 业务部 行政部

生产部 品保部 工程部







DOCUMENT NAME:	SUBJECT:		DOCUMENT NO:				
PRODUCT SPECIFICATION	RF I BOARD END		SPEC-1001				
	CONNECTOR	PAGE	3 OF 8	REV	Α		

1. SCOPE

This product described in this paper is a SMT Type Micro Coaxial RF Receptacle, whose part name in our comply is USS RF REC. It is special for micro strip-to -Coaxial adapter in RF circuit, such as Mobile Phone, Wireless Net, Mini PCI, Bluetooth, PDA, GPS, Electric Measurement Instruments and so on.

2. REQUIREMENT

2.1. PRODUCT DIMENSION

Product shall be intermateable with industry standard product of opposite gender. This connector shall have the dimensions as shown in Drawing .

2.2. PCB/PANEL LAYOUT

The recommended PCB layout are shown in Drawing.

2.3. BILL OF MATERIAL

The bill of material and product number of Connectors are described in Drawing .

2.4. MECHANICAL & ELECTRICAL CHARACTERISTIC

The connector shall have the mechanical and electrical performance as described in Table I.

2.5. PACKAGING

Parts shall be packaged according to requirements specified in purchase order for safe delivery. Connector container and the packing specification are shown in Drawing .

2.6. HARMFUL MATERIAL CONTROL

Harmful material controls please follow the **Doc. No. QW-QA-10.**

3. PERFORMANCE AND TEST DESCRIPTION

3.1. REQUIREMENT

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

3.2. TEST CONDITION

Unless otherwise specified, all tests shall be performed at ambient environmental conditions:

3.2.1 Temperature: **15**℃~**35**℃

3.2.2 Humidity: $50 \pm 2\%$ R.

3.2.3 Atmospheric Pressure: 650 mmHg to 800 mmHg.

3.3. SAMPLE SELECTION

Test samples shall be selected at random from current production. No test samples shall be reused. Each group shall be containing **10** test samples.

DOCUMENT NAME: PRODUCT SPECIFICATION

SUBJECT: RF I BOARD END CONNECTOR

DC		MENT SPEC-		•	
PΔ	GE	4 OI	F 8	REV	Α

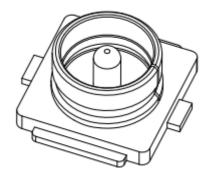
3.4 TEST SEQUENCE

Products qualification test sequence as shown in Table II.

4. QUALITY ASSURANCE PROVISIONS

CCT is responsible for the quality of the part as it is delivered to customer. The failing lots will be return or other supplier action.

5. PRODUCT PICTURE



6. Technical Parameters

6.1	Rated Voltage	60VAC (R.M.S)
0.1	1100000 1 0100000	00 1110 (1011110)

6.2 Frequency Range 0~6GHz

6.3 Character Impedance 50Ω

6.4 Operate Temperature -40°C~90°C
6.5 Operate Humidity 90% MAX

7. Electric Performance

7.1 Dielectric Resistance $500 \text{M}\,\Omega$

7.2 Dielectric Withstand Voltage 200VAC 1Min

7.3 Contact Resistance

7.3.1 Signal Contact Initial: $20m\Omega$ max

7.3.2 Ground Contact Initial: $20m \Omega$ max

7.4 VSWR

≦3GHz	3~6GHz
1.3max	1.4max

7.4.1 Test Method(Refer to the FIG2):



FIG2

DOCUMENT NAME:
PRODUCT SPECIFICATION

SUBJECT:

RF I BOARD END

CONNECTOR

DOCUMENT NO:
SPEC-1001

PAGE | 5 OF 8 | REV | A

Test Conditions				
	Specifications			
Solder the receptacle connector to the test board and mate the plug connector together, then measure the contact resistance as shown in Fig3 by the four terminal methods. Apply the low level conditions in accordance with MIL-STD-202G, Method 307.	Initial : $20 \text{m}\Omega$ MAX After testing : $\Delta R20 \text{ m}\Omega$ max [Ground contact]			
Open circuit voltage : 20 mV MAX Circuit current : 10 mA MAX	Initial : $20 \text{m}\Omega$ MAX After testing : $\Delta R20 \text{m}\Omega$ MAX			
Fig 3	Signal connector =A-B Ground contact =D-C			
Mate the receptacle and plug connector together, and then apply AC 200V rms between the signal contact and the ground contact for a minute in accordance with MIL-STD-202G, Method 301.	No creeping discharge, flashover no insulator breakdown shall occur.			
MIL-STD-202G, Method 301. Measure the VSWR as shown in FIG2 by the network analyzer. Frequency: 100M~6GHz 1.3MAX. at 0.1~3GHz 1.4MAX .at 3~6GHz				
Solder the receptacle connector to the test board and mate the plug connector, then measure the un-mating force at speed 25 ± 3 mm/minutes along by the push-pull machine.	[Total un-mating force] Initial :4N MIN After 30 :2N MIN			
Pull the cable as shown in Fig4 at speed 25 ± 3 mm/minutes by tensile strength machine.	8N MIN			
	as shown in Fig3 by the four terminal methods. Apply the low level conditions in accordance with MIL-STD-202G, Method 307. Open circuit voltage : 20 mV MAX Circuit current : 10 mA MAX Mate the receptacle and plug connector together, and then apply DC 100V between the signal contact and the ground contact in accordance with MIL-STD-202G, Method 302. Mate the receptacle and plug connector together, and then apply AC 200V rms between the signal contact and the ground contact for a minute in accordance with MIL-STD-202G, Method 301. Measure the VSWR as shown in FIG2 by the network analyzer. Frequency: 100M~6GHz Solder the receptacle connector to the test board and mate the plug connector, then measure the un-mating force at speed 25±3mm/minutes along by the push-pull machine. Pull the cable as shown in Fig4 at speed 25±			

OCUMENT NAMI		SUBJECT: RF I BOARD END	DOCU	DOCUMENT NO: SPEC-1001				
.02001 01 2011		CONNECTOR	PAGE	6 OF 8	REV	4		
7. Durability	the test board) ar 25 ± 3 mm/minute machine.	e the receptacle connector(soldered and plug connector 30 cycles at speed as along the mating by the push-pull	Contac	ance] No abn t Resistance] eet Table I.1	ormality			
8. Contact resistance with force on the cable		e cable as shown in Fig5 g, run 100mA DC to check electrical 2N MAX. Plug 2N MAX. Receptacle Fig5	[Electric No elect than 1 µ [Contact	ance] No abn al discontinuity rical discontinu s shall occur. t Resistance] leet Table I.1	y]	r		
9. Vibration	Apply the following vibration to the mating connector. During the testing, run 100mA DC to check electrical discontinuity. Frequency: 10Hz →100 Hz →10Hz/approx 20 minutes. Half amplitude, Peak value of acceleration : 1.5mm or 59m/s² (6G) Directions, cycle: 3 mutually perpendicular direction,3 cycles about each direction. Apply the following vibration to the mating connector. During the testing, run 100mA DC to check electrical [Appearance] No abnormality [Appearance] N					r		
10. Shock	Apply the following	[Contact Shall me [Electric No elect than 1 µ	ance] No abn t Resistance] et Table I.1 al discontinuity rical discontinu s shall occur.	y]	r			
11. Humidity (Steady State)	direction, 3cycle about each direction. Apply the following environment to the mating connector in accordance with MIL-STD-202G,Method 103, Condition B. Temperature : 313 ± 2 K (40 ± 2 °C) Humidity : $90\sim95$ %RH Duration : 96 hours [Appearance] No abnote [Contact Resistance] Shall meet Table I.1 [Insulation Resistance] Shall meet Table I.2 [Dielectric Withstanding Shall meet Table I.3.]					e]		
12. Thermal Shock	in accordance wit Condition A. Temperature Transition time	ng environment to the mating connect th MIL-STD-202G,Method 107G, : 218K (-55℃) →358K(85℃): 30n : 5min. MAX : 5 cycles	[Contact Shall min [Insulati Shall m	ance] No abn t Resistance] leet Table I.1 on Resistance leet Table I.2 ric Withstandin eet Table I.3.]	e]		

OCUMENT NAMI RODUCT SPECIF	 =	SUBJE(RF	CT: I BOARD END	DOCU	MENT NO SPEC-1001	DOCUMENT NO: SPEC-1001				
		CO	NNECTOR	PAGE	7 OF 8	REV	Α			
13. High Temperature Life	Temperature		ment to the mating connector $(90\pm2^{\circ})$	[Contact Shall me [Insulation Shall me	nce] No abnormation abnormatio]	÷]			
14. H₂S Gas	Temperature Relative Humidity Duration	: ' : :	96 hours	Contact Shall me [Insulation Shall me [Dielectric	nce] No abnormation abnormatio]	•]			
15. Salt Water Spray		.h MIL-STI : : :	ment to the mating connector D-202G, Method 101E, 308 ± 2 K (35 ± 2 °C) $95\sim98$ %RH 5 ± 1 %(by weight) 96 hours	[Appeara [Contact Shall me	nce] No abno Resistance] eet Table I.1	·				
16. Solder ability	Dip the solder tine of the contacts in the solder bath at 518±5K(245±5°C) for 5±0.5seconds after immersing the tine in the flux of RMA type for 5 to 10 seconds. More than 95% of the dipped surface shall be wet and less the surface shall be wet					less that	n			
	MIN .(225℃N (2) Pre-heat part * Refer to re	/IIN) 70sce : 433∼4 eflow temp	5 K($260+0$ /- 5 $^{\circ}$ C) Peak 498K e.MIN 43 K($160\sim170$ $^{\circ}$ C) $80\sim100$ s perature profile.(Fig6) w is within 2 times.	No abnorm	nality adverse		ing			
17. Soldering Heat Resistance	Fig 6	Temperature (K)	433~443K (160~170°C) 80~100sec.	(225°C) (225°C) (70sec	← 533K (260					